

### Radiation-Hardened Isolated DC-to-DC Converter

#### Introduction

The SA50 is an Isolated DC-to-DC converter capable of delivering up to 50W of output power in a small size design. The SA family provides a radiation hardened option with top class TID and SEE performance for space and military applications. With forward converter topology and a patented magnetic feedback scheme, the SA50 is optimized for applications where isolated DC voltage conversion is required. The discrete surface mount design facilitates customization with reasonable lead time and modest NRE cost.

The SA50 series implements an internal EMI input filter which complies to MIL-STD-461. The EMI filter consists of differential- and common-mode components to attenuate conductive EMI noise effectively.

As the only non-hybrid space grade DC-DC power converter module in the market, the SA50 series excels in its robustness in the applications with 8x10<sup>6</sup> hours of MTBF.

The SA50-120 is available in 3.055" x 2.055" x 0.5" package.

### **Table of Contents**

Intro	oduction	1
1.	Benefits and Features.	3
2.	Radiation Performance	4
3.	Typical Application circuit	5
4.	Absolute Maximum Ratings	6
5.	Electrical Parameters	7
6.	Radiation Specification (Note 1)	11
7.	Parallel operation (notes)	12
8.	Sample Electrical Waveforms	13
9.	Pin Configuration	14
10.	Pin Description	15
11.	Radiation Performance (-H) Hardened	16
12.	Radiation Performance (-P) Prototype	17
13.	Mechanical Outline (-A) Package	18
14.	Mechanical Outline (-B) Package	19
15.	Qualification Test (Reference Report QTR996)	20
16.	ATP Screening Test – (-HS) Hardened Standard	21
17.	ATP Screening Test – (-HE) Hardened Extended (Consult factory)	22
18.	ATP Screening Test (-P) Prototypes	23
19.	Ordering Information	24
20.	Contact Information	25
The	Microchip Website	26
Pro	duct Change Notification Service	26
Cus	stomer Support	26
Mic	rochip Devices Code Protection Feature	26
Leg	al Notice	27
Tra	demarks	27
Qua	ality Management System	28
Woı	rldwide Sales and Service	29

Datasheet

#### 1. Benefits and Features

- Up to 56W output Power (Parallel up to 5 for higher power)
- 86VDC to 158VDC input range
- 5 output configurations available

Output	Base Part number
3.3V	SA50-120-3R3S
5V	SA50-120-5S
12V	SA50-120-12S
15V	SA50-120-15S
28V	SA50-120-28S

- 85% efficiency @ full load
- <1% output ripple</p>
- · Internal EMI filter compliant to MIL-STD-461
- Forward topology
- · Patented magnetic feedback
- Adjustable output with remote adjust
- · Inhibit pin for electrical ON/OFF
- Isolated synchronization input
- Low mass of less than 120g
- Flight proven technology with >8 x 10<sup>6</sup> hours of MTBF
- This Product is classified as EAR99

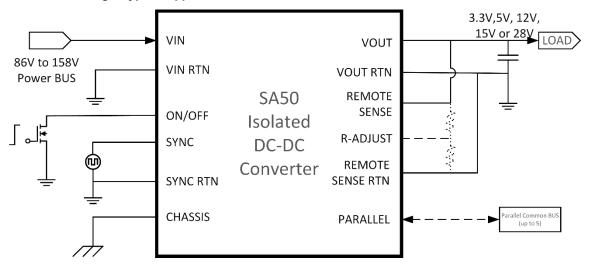
**Radiation Performance** 

#### 2. Radiation Performance

- TID>100krad(Si) and 30krad(Si) ELDRS (<10mrad/s) per MIL-STD-883 Method 1019
- SEE (SEGR, SEB, SET, SEL) immunity 82 MeV·cm<sup>2</sup>/mg

### 3. Typical Application circuit

Figure 3-1. SA50 Single Typical Application Circuit



# 4. Absolute Maximum Ratings

Rating	Value
V <sub>IN</sub> range	-0.5 VDC to 165 VDC
Output power	56 W
Lead temperature	300 °C for 10 s
Operating temperature	–55 °C to 125 °C
Storage temperature	–55 °C to 125 °C
Shock	1500 gpk, 0.5 ms, ½ sine
Constant acceleration	50 g
Random vibration	24.06 g <sub>rms</sub> , 50 Hz to 2000 Hz

#### 5. Electrical Parameters

This section shows the electrical parameters of the SA50-120 Single Series device under the following conditions unless otherwise specified:

Parameter	Output	Conditions	Min	Nom	Max	Units
Input voltage						
(Vin)		Note 2	86	120	158	V
Output voltage set po	int					
	28V		27.73	28.00	28.27	
	15V		14.85	15.00	15.15	_
(V <sub>OUT</sub> )	12V	I <sub>OUT</sub> = 100% rated load	11.88	12.00	12.12	V
	5V		5.05	5.10	5.15	
	3.3V		3.27	3.30	3.33	
Output Voltage Adjust						
(V <sub>ADJ</sub> )			10			%
Output power						
	28V	Note 13 In all cases Output power must be kept within P <sub>out</sub> rating.			56	
	15V		0		51	W
(P <sub>OUT</sub> )	12V				50	
	5V				50	
	3.3V				33	
Output current						
	28V				2.0	
	15V				3.4	
(I <sub>OUT</sub> )	12V		0		4.2	Α
	5V				10	
	3.3V				10	
Line regulation	Line regulation					
	28V		-56		56	
	15V	V <sub>IN</sub> = 86 V, 120 V, 158 V I <sub>OUT</sub> = 10%, 50%, 100%	-30		30	
(VR <sub>LINE</sub> )	12V		-24		24	mV
	5V	rated Note 12	_10		10	
	3.3V		-10		10	

continued						
Parameter	Output	Conditions	Min	Nom	Max	Units
Load regulation						
	28V		-280		280	
	15V	V <sub>IN</sub> = 86 V, 120 V, 158 V	-150		150	
(VR <sub>LOAD</sub> )	12V	I <sub>OUT</sub> = 10%, 50%, 100% rated Note 11	-120		120	mV
	5V	rated Note 11	<b>–</b> 50		50	
	3.3V		-50		50	
Input current						
(I <sub>IN</sub> )		I <sub>OUT</sub> =0, pin3 open		10	35	mA
('IN)		Pin 3 shorted to pin 2		3	5	ША
Output ripple						
	28V			100	280	
	15V	V <sub>IN</sub> = 86 V, 120 V, 158 V I <sub>OUT</sub> = 100% rated, Note 4		75	150	mV p-p
(V <sub>RIP</sub> )	12V			60	120	
	5V			25	50	
	3.3V			25	50	
Switching frequency						
(FS)		Sync input (pin 4) open	200	220	240	kHz
Efficiency						
	28V		79	85		
	15V		79	85		
(EFF)	12V	I <sub>OUT</sub> = 100% rated load	77	83		%
	5V		75	81		
	3.3V		73	79		
Inhibit input						
Inhibit input: ON Threshold		Note 1	4.5			V
Inhibit input: OFF (sink)		Note 1	1000			μA
Inhibit input: OFF Threshold		Note 1			2	V

continued						
Parameter	Output	Conditions	Min	Nom	Max	Units
Current limit point						
(% rated output)		When V <sub>OUT</sub> = 90% of nominal set point	105		145	%
Synchronization						
frequency range		The external clock on sync input (pin 4)	500		600	kHz
Synchronization pulse-high level		Note 1	4.0		10.0	V
Synchronization pulse-low level		Note 1	-0.5		0.5	V
Synchronization pulse-transition rate		Note 1	200			V/µs
Synchronization pulse-duty cycle		Note 1	10		80	%
Power dissipation, lo	ad fault					
(PD)		Short circuit, overload  Note 6			24	W
Output response to s	tep load cha	anges				
	28V		-2200		2200	
	15V		-1200		1200	
(V <sub>TLD</sub> )	12V	(50% to/from 100%) rated load Note 7	-900		900	mV peak
	5V	rated load Note 7	-300	-	300	
	3.3V		-300		300	
Recovery time, step I	oad change	s				
(T <sub>TLD</sub> )		(50% to/from 100%) rated load Notes 7, 8		200	2000	μs
Output response to s	tep line cha	nges			l	
	28V		-1000		1000	
	15V		-600		600	
(V <sub>TLN</sub> )	12V	86V to/from 158V I <sub>OUT</sub> = 100% rated load Note 9	-480		480	mV peak
	5V		-300		300	
	3.3V		-300		300	

### **Electrical Parameters**

continued						
Parameter	Output	Conditions	Min	Nom	Max	Units
Recovery time, step I	ine change	5				
(T <sub>TLN</sub> )		86V to/from 158V I <sub>OUT</sub> = 100% rated load Notes 8, 9		200	2000	μs
Turn-on response: ov	vershoot					
	28V				2800	
	15V				1500	
(V <sub>OS</sub> ) (main)	12V	(0% to 100%) rated load Notes 3, 4, 10			1200	mV
	5V				500	
	3.3V				500	
Turn-on response: tu	rn-on delay					
(T <sub>DLY</sub> )		Note 10	0.1		10	ms
Capacitive load	_					
	28V	Note 5			200	
	15V				350	μF
(CL)	12V				450	
	5V				1000	
	3.3V				1000	
Line rejection		'				
		DC to 50 kHz, I <sub>OUT</sub> = 100% rated load	30	60		dB
Isolation						
		200V @25°C  1. Input (1-3) to All (4-12)  2. Sync (4-5) to All (1-3, 6-12)  3. Chassis (6) to All (1-5, 7-12)	100			МΩ
Mass						
		Standard case style A, B			120	g
MTBF						
		MIL-HDBK-217F2, SF, 35°C		8.22E+06		hrs

#### 6. Radiation Specification (Note 1)

Environment	Conditions	Min	Unit
TID (gamma)	MIL-STD-883, method 1019 The operating bias applied during exposure	100	krad (Si)
Dose rate (gamma dot temporary saturation survival)	MIL-STD-883, method 1023 The operating bias applied during exposure Full-rated load	1E10	rad (Si)/s
Neutron fluence	MIL-STD-883, 1017	1E12	Neutrons
SEE/SEU, SEL, SEGR, SEB (H – Hardened)	Heavy ions [LET] The operating bias applied during exposure	82	MeV•cm²/mg

#### Notes:

- 1. Parameter guaranteed by design.
- 2. Parameter verified during line and load regulation tests. Regulation is specified for 10% to 100% loading on all outputs.
- 3. The "-HS/-HE" option incorporates FET technology providing a > 82 MeV•cm2/mg (gold ion) SEE capability to the design. The "-P" option is not rated for radiation.
- 4. Guaranteed for a DC to 20 MHz bandwidth. Tested using a 20 kHz to 10 MHz bandwidth. Ripple is measured across a 50 Ohms termination with a 10nF Cap in series.
- 5. The capacitive load may be any value from 0 to the maximum limit without compromising DC performance. A capacitive load exceeding the maximum limit may interfere with the proper operation of the converter's overload protection. This situation may cause erratic behavior during turn-on.
- 6. Overload power dissipation is defined as the device power dissipation with the load set such that VOUT = 90% of nominal.
- 7. The load step transition time is  $\ge 10 \, \mu s$ .
- 8. Recovery time is measured from the initiation of the transient to where VOUT has returned to within ±1% of its steady-state value.
- 9. The line step transition time is  $\geq$  100  $\mu$ s.
- 10. Turn-on delay time from either a step application of input power or a logic low to a logic high transition on the inhibit pin (pin 3) to the point where VOUT = 90% of nominal.
- 11. Load regulation relative to the output voltage at 50% rated load.
- 12. Line regulation relative to the output voltage at 120 VDC input.
- 13. For operation at temperatures between 85  $^{\circ}$ C and 125  $^{\circ}$ C: de-rate power linearly from 50 W (or rated maximum) to zero. Parameter limits are not guaranteed.

Parallel operation (notes)

#### 7. Parallel operation (notes)

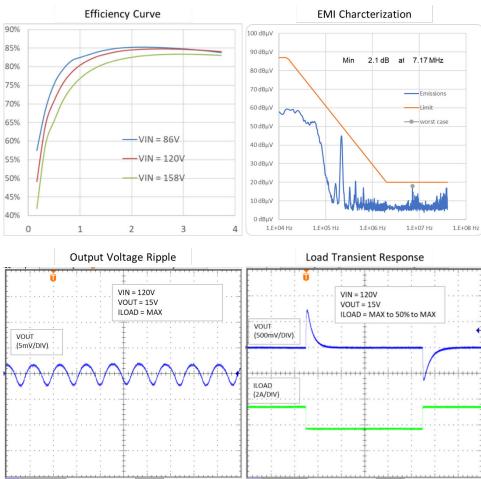
The output terminals of up to 5 modules may be connected in parallel. The expected current sharing accuracy is 10% at maximum load. To ensure current sharing, the Parallel terminal of every Power Supply module must be connected to form a common bus. These connections should be made relatively short.

The remote sense terminals may remain unconnected. For best output voltage regulation however, the remote sense terminal of each of the paralleled set of Power Supplies should be connected to a single point, as close as possible to the positive load terminal or point where the voltage regulation is desired to be maintained. Similarly, the remote sense return terminal of each Power Supply should be connected to a single point, as close as possible to the negative load terminal.

The R-ADJUST function may be used in a system of paralleled modules. The sync function is described in the application notes. The specified sync input signal may be applied to each of the paralleled modules.

For best performance, phase shift the sync signal between modules. The sync functionality remains the same for a system of paralleled modules. The use of the sync function is optional for single and or paralleled operation. The specified sync input signal may be applied to any one of the paralleled modules.

### 8. Sample Electrical Waveforms



### 9. Pin Configuration

Figure 9-1. SA50 Single Pin Configuration



## 10. Pin Description

PIN	NAME	Description
1	VIN	Input Voltage
2	VIN RTN	Input Voltage Return/Ground
3	ON/OFF (INHIBIT)	Power Supply ON/OFF, ON(OPEN/HIGH), OFF(SHORT/LOW)
4	SYNC	External Clock Signal Input
5	SYNC RTN	External Clock Signal Return
6	CHASSIS	Chassis Pin
7	R-ADJUST	Remote Adjust Pin to Adjust Output Voltage ±10%
8	PARALLEL	Parallel Bus Pin to use Multiple Devices for Higher Power
9	RMT SNS RTN	Load Voltage Remote Sense Return
10	RMT SNS	Load Voltage Remote Sense
11	VOUT	Output Voltage
12	VOUT RTN	Output Voltage Return/Ground

Radiation Performance (-H) Hardened

### 11. Radiation Performance (-H) Hardened

- TID>100krad(Si) and 30krad(Si) ELDRS (<10mrad/s) per MIL-STD-883 Method 1019
- SEE (SEGR, SEB, SET, SEL) immunity 82 MeV·cm<sup>2</sup>/mg (H-hardened)

Radiation Performance (-P) Prototype

### 12. Radiation Performance (-P) Prototype

Prototype units that are functionally the same except that components are not radiation hardened. To be used for system checkout.

### 13. Mechanical Outline (-A) Package

Figure 13-1. Side Pins and Thru-Hole Tabs Package

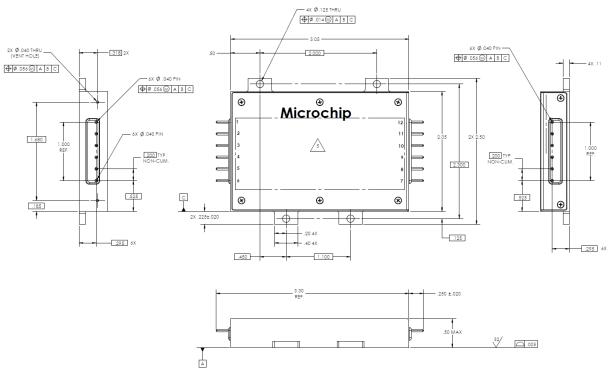
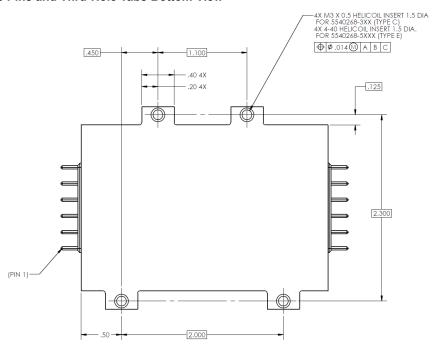


Figure 13-2. Side Pins and Thru-Hole Tabs Bottom View



### 14. Mechanical Outline (-B) Package

Figure 14-1. Top Pins and Threaded Package

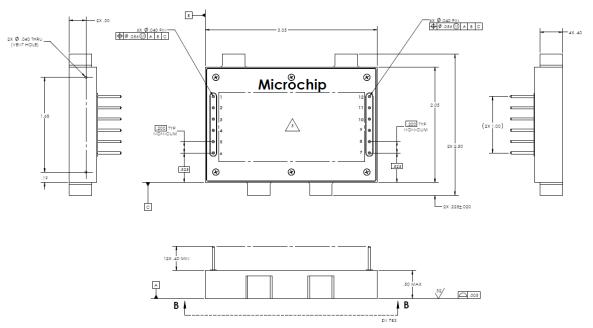
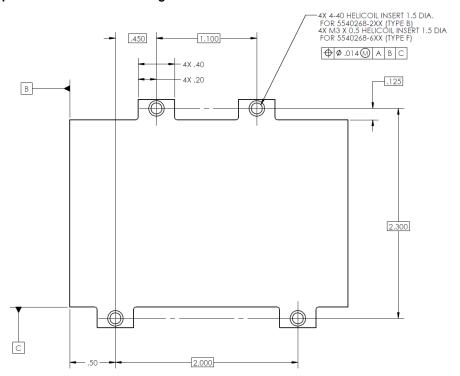


Figure 14-2. Top Pins and Threaded Package Bottom View



## 15. Qualification Test (Reference Report QTR996)

Test	Conditions	Method	Notes
External visual	Per O&M—dimensions, and mass or STD 883 2009	Inspection	Appendix A
Electrical	Read and record (–55 °C, 25 °C, 85 °C)	Test	Appendix D
Shock, non- operating	MIL-STD-202, method 213B, test condition F, 1500 gpk, 0.5 ms ½ sine pulse.  Three pulses in each direction of each axis, 18 pulses total.	Test	Appendix B
Vibration, operating	MIL-STD-202, method 214A, condition II-F, 24.06 grms random vibrations, 50 Hz–2000 Hz, 3 min/axis (9 min total).  Outputs monitored.	Test	Appendix C
Thermal vacuum	MIL-STD-883, method 1001, condition G, three cycles with a base plate temperature of –55 °C to 85 °C.  Outputs monitored during TVAC cycles, record at temperatures noted under electrical.	Test, Increased temperature in lieu of vacuum	Appendix D Certification TVAC Testing pending
Temperature cycling	10 cycles from base plate temperature, MIL-STD-883, method 1010.9, condition C	Test	Appendix D
ЕМІ	CE101, CE102, CS101, RE101, RE102, RS101, RS102 per MIL-STD-461 with setup per MIL-STD-462.	Analysis & Test	Appendix E  Certification EMI Testing pending
External Visual inspection	No damage	Inspection	Appendix A
Steady state life test	1000 hrs at Tc = 105 °C, 50% of rated load	Analysis, Extended Screening Test Heritage	Validation Test Pending
End-point electricals	Read and record ( –55 °C, 25 °C, 85 °C)	Test	Appendix D

## 16. ATP Screening Test – (-HS) Hardened Standard

Requirement	Test Method/Condition
External Visual	O&M – dimensions and mass
Initial Electrical	Full perfomance at +25°C
Vibration	Workmanship non-operating vibration. MIL-STD-202, Method 214, 6 grms (50Hz-2kHz) 1-minute perpendicular to the board
Post Vibration Electrical	Full perfomance at +25°C
Temperature Cycle	MIL-STD-883, Method 1010, Condition A, 1 cycle, +85°C to -55°C, operating Outputs monitored during thermal cycles
Burn-in	40 Hrs @ 105°C, 50% of rated load (outputs monitored)
Final Electrical	Full performance at +25°C (deliverable data)
External Visual	No damage

## 17. ATP Screening Test – (-HE) Hardened Extended (Consult factory)

Requirement	Test Method/Condition
External Visual	O&M – dimensions and mass
Initial Electrical	Full perfomance at +25°C
Vibration	Workmanship operating vibration. MIL-STD-202, Method 214, 6 grms (50Hz-2kHz) 1-minute perpendicular to the board
Post Vibration Electrical	Full perfomance at +25°C
Temperature Cycle	MIL-STD-883, Method 1010, Condition A, 10 cycle, +85°C to -55°C, operating Outputs monitored during thermal cycles
Burn-in	160 Hrs @ 105°C, 50% of rated load (outputs monitored)
Final Electrical	Full performance at -55°C, +25°C, and +85°C (deliverable data)
External Visual	No damage

## 18. ATP Screening Test (-P) Prototypes

Requirement	Test Method/Condition
External Visual	O&M – dimensions and mass
Electrical	Full performance at +85°C, +25°C55°C for initial first article of SA50
	Full performance at +25°C for previously qualified variation of SA50
Vibration	None
Temperature Cycle	None
Burn-in	None
External Visual	No damage

### 19. Ordering Information

The following chart defines the part number nomenclature of the **SA50-120** Single Series device.

Example part number: SA50-120-5S-C-HS

Model	SA50-120	Standard Applications 50W, 120V input modules. (Other models and input voltages available)			
Main	-3R3S	3.3V	Main output voltage		
	-58	5V			
	-128	12V			
	-158	15V			
	-28S	28V			
Mechanical Package	-A	Side,	0.125in through	Mechanical packaging options.	
	-B	Тор	4-40 thread		
	-C	Side	M3 thread	Electrical connections are either through the Top or the Side. And mounting holes are drilled through or tapped.	
	-D	Тор	0.125in through		
	-E	Side	4-40 thread		
	-F	Тор	M3 thread		
Radiation Hardness	-HS	Hardened	We offer units with radiation hardened components in either standard screening or Extended screening. We also offer lower cost Prototype units meant for system design verification that are not radiation hardened.		
		Standard			
	-HE	Hardened Extended			
	-P	Prototype			

NOTE: Microchip currently offers four models: SA50-120 Single, SA50-120 Triple, SA50-28 Single and SA50-28 Triple. We also offer customization design services, for changes in input volage, output voltages, or screening, Please contact us for more information.

We also offer a thermal interface the ST-2X3, this is a non-silicon space approved thermal interface, Datasheet available upon request.

#### 20. Contact Information

Jan Fox

Project Manager / SA50 Products

Microchip Technology Inc.

11861 Western Ave., Garden Grove, CA 92841 USA

+1.714.799.6514

jan.fox@microchip.com

### The Microchip Website

Microchip provides online support via our website at <a href="www.microchip.com/">www.microchip.com/</a>. This website is used to make files and information easily available to customers. Some of the content available includes:

- Product Support Data sheets and errata, application notes and sample programs, design resources, user's
  guides and hardware support documents, latest software releases and archived software
- General Technical Support Frequently Asked Questions (FAQs), technical support requests, online discussion groups, Microchip design partner program member listing
- Business of Microchip Product selector and ordering guides, latest Microchip press releases, listing of seminars and events, listings of Microchip sales offices, distributors and factory representatives

#### **Product Change Notification Service**

Microchip's product change notification service helps keep customers current on Microchip products. Subscribers will receive email notification whenever there are changes, updates, revisions or errata related to a specified product family or development tool of interest.

To register, go to www.microchip.com/pcn and follow the registration instructions.

#### **Customer Support**

Users of Microchip products can receive assistance through several channels:

- · Distributor or Representative
- · Local Sales Office
- Embedded Solutions Engineer (ESE)
- Technical Support

Customers should contact their distributor, representative or ESE for support. Local sales offices are also available to help customers. A listing of sales offices and locations is included in this document.

Technical support is available through the website at: www.microchip.com/support

### Microchip Devices Code Protection Feature

Note the following details of the code protection feature on Microchip devices:

- · Microchip products meet the specifications contained in their particular Microchip Data Sheet.
- Microchip believes that its family of products is secure when used in the intended manner and under normal conditions.
- There are dishonest and possibly illegal methods being used in attempts to breach the code protection features
  of the Microchip devices. We believe that these methods require using the Microchip products in a manner
  outside the operating specifications contained in Microchip's Data Sheets. Attempts to breach these code
  protection features, most likely, cannot be accomplished without violating Microchip's intellectual property rights.
- · Microchip is willing to work with any customer who is concerned about the integrity of its code.
- Neither Microchip nor any other semiconductor manufacturer can guarantee the security of its code. Code
  protection does not mean that we are guaranteeing the product is "unbreakable." Code protection is constantly
  evolving. We at Microchip are committed to continuously improving the code protection features of our products.
  Attempts to break Microchip's code protection feature may be a violation of the Digital Millennium Copyright Act.
  If such acts allow unauthorized access to your software or other copyrighted work, you may have a right to sue
  for relief under that Act.

#### **Legal Notice**

Information contained in this publication is provided for the sole purpose of designing with and using Microchip products. Information regarding device applications and the like is provided only for your convenience and may be superseded by updates. It is your responsibility to ensure that your application meets with your specifications.

THIS INFORMATION IS PROVIDED BY MICROCHIP "AS IS". MICROCHIP MAKES NO REPRESENTATIONS OR WARRANTIES OF ANY KIND WHETHER EXPRESS OR IMPLIED, WRITTEN OR ORAL, STATUTORY OR OTHERWISE, RELATED TO THE INFORMATION INCLUDING BUT NOT LIMITED TO ANY IMPLIED WARRANTIES OF NON-INFRINGEMENT, MERCHANTABILITY, AND FITNESS FOR A PARTICULAR PURPOSE OR WARRANTIES RELATED TO ITS CONDITION, QUALITY, OR PERFORMANCE.

IN NO EVENT WILL MICROCHIP BE LIABLE FOR ANY INDIRECT, SPECIAL, PUNITIVE, INCIDENTAL OR CONSEQUENTIAL LOSS, DAMAGE, COST OR EXPENSE OF ANY KIND WHATSOEVER RELATED TO THE INFORMATION OR ITS USE, HOWEVER CAUSED, EVEN IF MICROCHIP HAS BEEN ADVISED OF THE POSSIBILITY OR THE DAMAGES ARE FORESEEABLE. TO THE FULLEST EXTENT ALLOWED BY LAW, MICROCHIP'S TOTAL LIABILITY ON ALL CLAIMS IN ANY WAY RELATED TO THE INFORMATION OR ITS USE WILL NOT EXCEED THE AMOUNT OF FEES, IF ANY, THAT YOU HAVE PAID DIRECTLY TO MICROCHIP FOR THE INFORMATION. Use of Microchip devices in life support and/or safety applications is entirely at the buyer's risk, and the buyer agrees to defend, indemnify and hold harmless Microchip from any and all damages, claims, suits, or expenses resulting from such use. No licenses are conveyed, implicitly or otherwise, under any Microchip intellectual property rights unless otherwise stated.

#### **Trademarks**

The Microchip name and logo, the Microchip logo, Adaptec, AnyRate, AVR, AVR logo, AVR Freaks, BesTime, BitCloud, chipKIT, chipKIT logo, CryptoMemory, CryptoRF, dsPIC, FlashFlex, flexPWR, HELDO, IGLOO, JukeBlox, KeeLoq, Kleer, LANCheck, LinkMD, maXStylus, maXTouch, MediaLB, megaAVR, Microsemi, Microsemi logo, MOST, MOST logo, MPLAB, OptoLyzer, PackeTime, PIC, picoPower, PICSTART, PIC32 logo, PolarFire, Prochip Designer, QTouch, SAM-BA, SenGenuity, SpyNIC, SST, SST Logo, SuperFlash, Symmetricom, SyncServer, Tachyon, TimeSource, tinyAVR, UNI/O, Vectron, and XMEGA are registered trademarks of Microchip Technology Incorporated in the U.S.A. and other countries.

AgileSwitch, APT, ClockWorks, The Embedded Control Solutions Company, EtherSynch, FlashTec, Hyper Speed Control, HyperLight Load, IntelliMOS, Libero, motorBench, mTouch, Powermite 3, Precision Edge, ProASIC, ProASIC Plus, ProASIC Plus logo, Quiet-Wire, SmartFusion, SyncWorld, Temux, TimeCesium, TimeHub, TimePictra, TimeProvider, WinPath, and ZL are registered trademarks of Microchip Technology Incorporated in the U.S.A.

Adjacent Key Suppression, AKS, Analog-for-the-Digital Age, Any Capacitor, Anyln, AnyOut, Augmented Switching, BlueSky, BodyCom, CodeGuard, CryptoAuthentication, CryptoAutomotive, CryptoCompanion, CryptoController, dsPICDEM, dsPICDEM.net, Dynamic Average Matching, DAM, ECAN, Espresso T1S, EtherGREEN, IdealBridge, In-Circuit Serial Programming, ICSP, INICnet, Intelligent Paralleling, Inter-Chip Connectivity, JitterBlocker, maxCrypto, maxView, memBrain, Mindi, MiWi, MPASM, MPF, MPLAB Certified logo, MPLIB, MPLINK, MultiTRAK, NetDetach, Omniscient Code Generation, PICDEM, PICDEM.net, PICkit, PICtail, PowerSmart, PureSilicon, QMatrix, REAL ICE, Ripple Blocker, RTAX, RTG4, SAM-ICE, Serial Quad I/O, simpleMAP, SimpliPHY, SmartBuffer, SMART-I.S., storClad, SQI, SuperSwitcher, SuperSwitcher II, Switchtec, SynchroPHY, Total Endurance, TSHARC, USBCheck, VariSense, VectorBlox, VeriPHY, ViewSpan, WiperLock, XpressConnect, and ZENA are trademarks of Microchip Technology Incorporated in the U.S.A. and other countries.

SQTP is a service mark of Microchip Technology Incorporated in the U.S.A.

The Adaptec logo, Frequency on Demand, Silicon Storage Technology, and Symmcom are registered trademarks of Microchip Technology Inc. in other countries.

GestIC is a registered trademark of Microchip Technology Germany II GmbH & Co. KG, a subsidiary of Microchip Technology Inc., in other countries.

All other trademarks mentioned herein are property of their respective companies.

© 2021, Microchip Technology Incorporated, Printed in the U.S.A., All Rights Reserved.

ISBN: 978-1-5224-7850-8

# **Quality Management System**

For information regarding Microchip's Quality Management Systems, please visit www.microchip.com/quality.



# **Worldwide Sales and Service**

AMERICAS	ASIA/PACIFIC	ASIA/PACIFIC	EUROPE
Corporate Office	Australia - Sydney	India - Bangalore	Austria - Wels
2355 West Chandler Blvd.	Tel: 61-2-9868-6733	Tel: 91-80-3090-4444	Tel: 43-7242-2244-39
Chandler, AZ 85224-6199	China - Beijing	India - New Delhi	Fax: 43-7242-2244-393
Tel: 480-792-7200	Tel: 86-10-8569-7000	Tel: 91-11-4160-8631	Denmark - Copenhagen
Fax: 480-792-7277	China - Chengdu	India - Pune	Tel: 45-4485-5910
Technical Support:	Tel: 86-28-8665-5511	Tel: 91-20-4121-0141	Fax: 45-4485-2829
www.microchip.com/support	China - Chongqing	Japan - Osaka	Finland - Espoo
Web Address:	Tel: 86-23-8980-9588	Tel: 81-6-6152-7160	Tel: 358-9-4520-820
www.microchip.com	China - Dongguan	Japan - Tokyo	France - Paris
Atlanta	Tel: 86-769-8702-9880	Tel: 81-3-6880- 3770	Tel: 33-1-69-53-63-20
Duluth, GA	China - Guangzhou	Korea - Daegu	Fax: 33-1-69-30-90-79
Tel: 678-957-9614	Tel: 86-20-8755-8029	Tel: 82-53-744-4301	Germany - Garching
Fax: 678-957-1455	China - Hangzhou	Korea - Seoul	Tel: 49-8931-9700
Austin, TX	Tel: 86-571-8792-8115	Tel: 82-2-554-7200	Germany - Haan
Tel: 512-257-3370	China - Hong Kong SAR	Malaysia - Kuala Lumpur	Tel: 49-2129-3766400
Boston	Tel: 852-2943-5100	Tel: 60-3-7651-7906	Germany - Heilbronn
Westborough, MA	China - Nanjing	Malaysia - Penang	Tel: 49-7131-72400
Tel: 774-760-0087	Tel: 86-25-8473-2460	Tel: 60-4-227-8870	Germany - Karlsruhe
Fax: 774-760-0088	China - Qingdao	Philippines - Manila	Tel: 49-721-625370
Chicago	Tel: 86-532-8502-7355	Tel: 63-2-634-9065	Germany - Munich
Itasca, IL	China - Shanghai	Singapore	Tel: 49-89-627-144-0
Tel: 630-285-0071	Tel: 86-21-3326-8000	Tel: 65-6334-8870	Fax: 49-89-627-144-44
Fax: 630-285-0075	China - Shenyang	Taiwan - Hsin Chu	Germany - Rosenheim
Dallas	Tel: 86-24-2334-2829	Tel: 886-3-577-8366	Tel: 49-8031-354-560
Addison, TX	China - Shenzhen	Taiwan - Kaohsiung	Israel - Ra'anana
Tel: 972-818-7423	Tel: 86-755-8864-2200	Tel: 886-7-213-7830	Tel: 972-9-744-7705
Fax: 972-818-2924	China - Suzhou	Taiwan - Taipei	Italy - Milan
Detroit	Tel: 86-186-6233-1526	Tel: 886-2-2508-8600	Tel: 39-0331-742611
Novi, MI	China - Wuhan	Thailand - Bangkok	Fax: 39-0331-466781
Tel: 248-848-4000	Tel: 86-27-5980-5300	Tel: 66-2-694-1351	Italy - Padova
Houston, TX	China - Xian	Vietnam - Ho Chi Minh	Tel: 39-049-7625286
Tel: 281-894-5983	Tel: 86-29-8833-7252	Tel: 84-28-5448-2100	Netherlands - Drunen
Indianapolis	China - Xiamen		Tel: 31-416-690399
Noblesville, IN	Tel: 86-592-2388138		Fax: 31-416-690340
Tel: 317-773-8323	China - Zhuhai		Norway - Trondheim
Fax: 317-773-5453	Tel: 86-756-3210040		Tel: 47-72884388
Tel: 317-536-2380			Poland - Warsaw
Los Angeles			Tel: 48-22-3325737
Mission Viejo, CA			Romania - Bucharest
Tel: 949-462-9523			Tel: 40-21-407-87-50
Fax: 949-462-9608			Spain - Madrid
Tel: 951-273-7800 Raleigh, NC			Tel: 34-91-708-08-90
• .			Fax: 34-91-708-08-91
Tel: 919-844-7510 New York, NY			Sweden - Gothenberg Tel: 46-31-704-60-40
Tel: 631-435-6000			Sweden - Stockholm
San Jose, CA			Tel: 46-8-5090-4654
Tel: 408-735-9110			UK - Wokingham
Tel: 408-436-4270			Tel: 44-118-921-5800
Canada - Toronto			Fax: 44-118-921-5820
Tel: 905-695-1980			1 ax. 77-110-321-0020
Fax: 905-695-2078			
1 dx. 505-050-2010			